

Attorney Docket: 2022/48819
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Bulent M. Basol et al.

Serial No.: 09/671,800

Group Art Unit: 3723

Filed: September 28, 2000

Examiner: Not Yet Assigned

Title: PROCESS TO MINIMIZE AND/OR ELIMINATE CONDUCTIVE MATERIAL
COATING OVER THE TOP SURFACE OF A PATTERNED SUBSTRATE
AND LAYER STRUCTURE MADE THEREBY

ADDITIONAL CLAIMS FEE CHART

Commissioner for Patents
Washington, D.C. 20231

Transmitted herewith is a Preliminary Amendment for
filing and the filing fee is calculated below:

For	No. After Amendment	Highest No. Prev. Filed	No. Extra	Rate	Fee
Total Claims	38	22	16	\$ 9/\$18 =	\$144
Indep. Claims	3	3	2	\$40/\$80 =	\$
TOTAL:					\$144

XX A check in the amount of \$144.00 is enclosed.

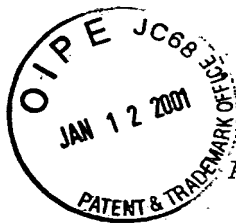
XX The Commissioner is hereby authorized to charge any additional
fees which may be required, or credit any overpayment, to
Account No. 05-1323 (Docket #2022/48819). A duplicate copy
of this sheet is attached.

Respectfully submitted,

January 12, 2001

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Registration No. 32,390

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#3 Pre Amend A
L. Nelson
1/23/01

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Please add the following new claims prior to examination:

A1 --23. A process of making a layer structure usable in
manufacturing an integrated circuit comprising:

producing, in a single apparatus, a structure having
deposits of conductive material in features defined in a
patterned substrate which are physically isolated from each other
by providing said patterned substrate, supplying an electrolyte
solution out of which said conductive material can be plated,
under an applied potential, over a surface of said patterned
substrate, applying a potential so as to deposit a film of said
conductive material out of the electrolyte solution and over said
surface of said patterned substrate and polishing the film of
said conductive material, and removing said conductive material
from field regions of said patterned substrate while leaving said
deposits of said conductive material in said features defined in
said patterned substrate; and